LP211, LP311 LOW-POWER DIFFERENTIAL COMPARATORS WITH STROBES

SLCS003D - JUNE 1987 - REVISED SEPTEMBER 2003

- Low Power Drain . . . 900 μW Typical With 5-V Supply
- Operates From ±15 V or From a Single Supply as Low as 3 V
- Output Drive Capability of 25 mA
- Emitter Output Can Swing Below Negative Supply
- Response Time . . . 1.2 μs Typ
- Low Input Currents:

Offset Current ... 2 nA Typ Bias Current ... 15 nA Typ

- Wide Common-Mode Input Range:
 -14.5 V to 13.5 V Using ±15-V Supply
- Offset Balancing and Strobe Capability
- Same Pinout as LM211, LM311
- Designed To Be Interchangeable With Industry-Standard LP311

description/ordering information

The LP211 and LP311 devices are low-power versions of the industry-standard LM211 and LM311 devices. They take advantage of stable, high-value, ion-implanted resistors to perform the same function as the LM311 series, with a 30:1 reduction in power consumption, but only a 6:1 slowdown in response time. They are well suited for battery-powered applications and all other applications where fast response times are not needed. They operate over a wide range of supply voltages, from ±18 V down to a single 3-V supply with less than 300-µA current drain, but are still capable of driving a 25-mA load. The LP211 and LP311 are quite easy to apply free of oscillation if ordinary precautions are taken to minimize stray coupling from the output to either input or to the trim pins. In addition, offset balancing is available to minimize input offset voltage. Strobe capability also is provided to turn off the output (regardless of the inputs) by pulling the strobe pin low.

The LP211 is characterized for operation from –25°C to 85°C. The LP311 is characterized for operation from 0°C to 70°C.

ORDERING INFORMATION

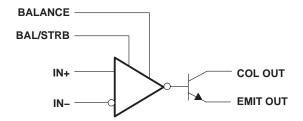
TA	V _{IO} max AT 25°C	PACKAGE [†]		PACKAGE [†] ORDERABLE PART NUMBER	
		PDIP (P)	Tube of 50	LP311P	LP311P
−0°C to 70°C	7.5 mV	SOIC (D)	Tube of 75	LP311D	1 D044
			Reel of 2500	LP311DR	LP311
		SOP (PS)	Reel of 2000	LP311PSR	L311
–25°C to 85°C	7.5 mV	SOIC (D)	Tube of 75	LP211D	L D044
			Reel of 2500	LP211DR	LP211

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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functional block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

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Supply voltage (see Note 1): V _{CC+}		10 V
V _{CC}		18 V
Differential input voltage, V _{ID} (see Note 2)		±30 V
Input voltage, V _I (either input, see Notes 1 and 3)		±15 V
Voltage from emitter output to V _{CC}		30 V
Voltage from collector output to V _{CC}		40 V
Voltage from collector output to emitter output		40 V
Duration of output short circuit (see Note 4)		40 V
Package thermal impedance, θ_{JA} (see Notes 5 and 6)	: D package	97°C/W
	P package	85°C/W
	PS package	95°C/W
Operating virtual junction temperature, T _J		150°C
Storage temperature range, T _{stg}		-65°C to 150°C

[†] Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the recommended operating conditions section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, unless otherwise noted, are with respect to the midpoint between V_{CC+} and V_{CC-}
 - 2. Differential input voltages are at IN+ with respect to IN-.
 - 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage of ±15 V, whichever is less.
 - 4. The output may be shorted to ground or to either power supply.
 - 5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 6. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	MAX	UNIT
(V _{CC±} ≤ 15 V)	Input voltage	V _{CC} ₋ + 0.5	V _{CC+} – 1.5	V
V _{CC+} - V _{CC} -	Supply voltage	3.5	30	V



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electrical characteristics at specified free-air temperature, $V_{CC\pm}$ = ± 15 V (unless otherwise noted)

	PARAMETER	TEST CON	DITIONS	TA	MIN	TYP†	MAX	UNIT
\/	lanut effect voltege	DC .400 l-0	See Note 7	25°C		2	7.5	mV
V_{ID}	Input offset voltage	RS < 100 kΩ,	See Note 7	Full range			10	IIIV
		V _{ID} < -10 mV, See Note 8	$I_{OL} = 25 \text{ mA},$	25°C		0.4	1.5	
VOL	Low-level output voltage	$V_{CC} = 4.5 \text{ V},$ $V_{ID} < -10 \text{ mV},$ See Note 8	$V_{CC-} = 0,$ $I_{OL} = 1.6 \text{ mA},$	Full range		0.1	0.4	V
	land Matauman	0 N-1 - 7		25°C		2	25	nA
ΙΟ	Input offset current	See Note 7		Full range			35	
				25°C		15	100	4
ΙΒ	Input bias current			Full range			150	nA
	Low-level strobe current	V _(strobe) = 0.3 V, See Note 9	V_{ID} < -10 mV,	25°C		100	300	μΑ
I _{O(off)}	Output off-state current	V _{ID} > 10 mV,	V _{CE} = 35 V	25°C		0.2	100	nA
A _{VD}	Large-signal differential-voltage amplification	R _L = 5 kΩ		25°C	40	100		V/mV
I _{CC+}	Supply current from V _{CC+}	$V_{ID} = -50 \text{ mV},$	R _L = ∞	Full range		150	300	μΑ
ICC-	Supply current from V _{CC} -	V _{ID} = 50 mV,	R _L = ∞	Full range		- 80	- 180	μΑ

[†] All typical values are at $V_{CC\pm}$ = ±15 V, T_A = 25°C.

NOTES: 7. The offset voltages and offset currents given are the maximum values required to drive the output within 1 V of either supply with a 1-mA load. Thus, these parameters define an error band and take into account the worst-case effects of voltage gain and input impedance.

- 8. Voltages are with respect to EMIT OUT and V_{CC-} tied together.
- 9. The strobe should not be shorted to ground; it should be current driven at 100 μA to 300 μA .

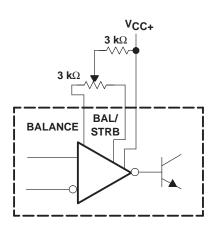
switching characteristics, $V_{CC\pm}$ = ± 5 V, T_A = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TYP	UNIT
Response time	See Note 10	1.2	μs

NOTE 10: The response time is specified for a 100-mV input step with 5-mV overdrive.

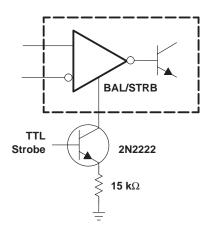


TYPICAL APPLICATION CIRCUIT



NOTE: If offset balancing is not used, the BALANCE and BAL/STRB pins should be shorted together.

Figure 1. Offset Balancing



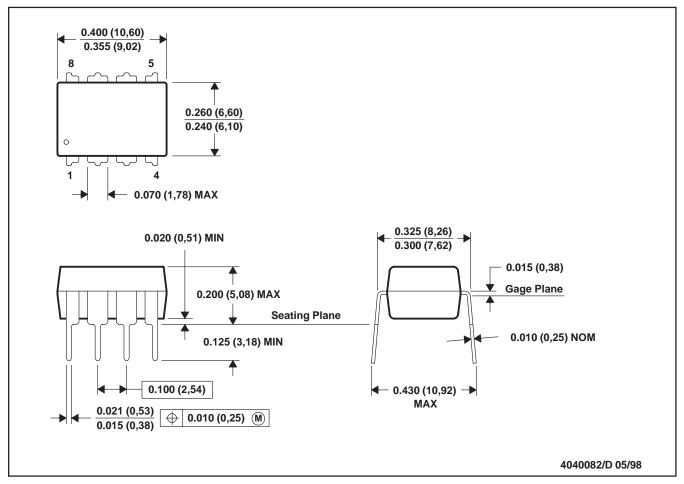
NOTE: Do not connect strobe pin directly to ground, because the output is turned off whenever current is pulled from the strobe pin.

Figure 2. Strobing



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



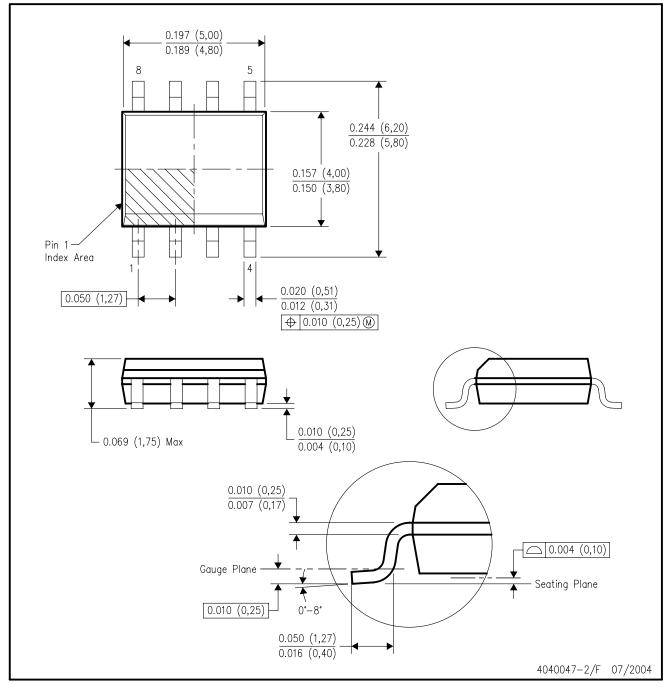
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to $http://www.ti.com/sc/docs/package/pkg_info.htm$

D (R-PDSO-G8)

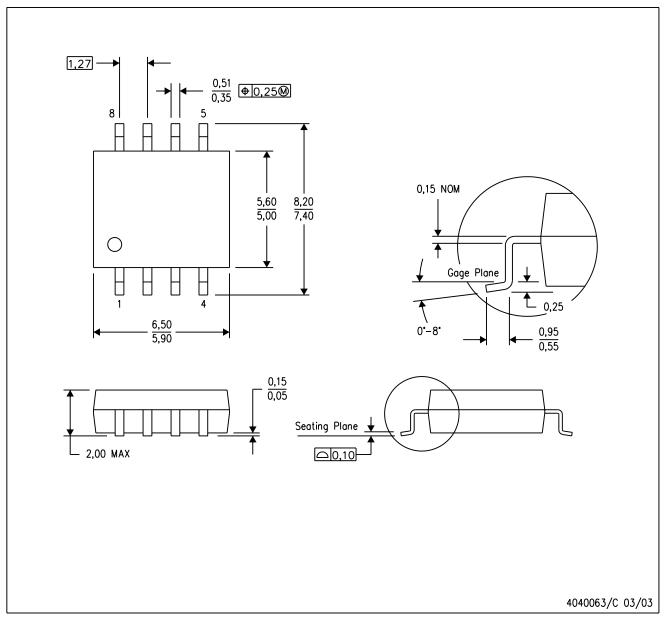
PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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